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Call for Papers

2018 IEEE NorCAS Conference

IEEE Nordic Circuits and Systems Conference
30-31 October 2018, Tallinn, Estonia

General Scope of the Conference

The IEEE NorCAS conference is the main circuits and systems event of the Nordic countries representing both academia as well as electronics industry. The IEEE NorCAS conference is a merge of the well-established conferences NORCHIP and SoC. The annual IEEE CAS sponsored conference covers all fields of electronics design, spanning from complex digital systems to advanced analog and mixed-mode circuits. The wide scope of the conference promotes cross-field collaboration not only between academics but also with industry. Papers of high scientific and technical quality are presented together with selected invited speakers and pre-conference tutorial sessions.

Technical programme

The 2018 NorCAS conference will take place on 30-31 October 2018. The Steering Committee invites people from academia and industry to contribute papers. Contributions for the 2018 conference in Tallinn should be in the following areas:

ANALOG

- Biomedical Circuits and Systems
- Sensor interface circuits, data-converters
- Wireless Circuits and Systems
- Mixed mode designs, high frequency circuits, design for testability

DIGITAL

- Microelectronics/nanoelectronics
- Embedded systems, FPGA and rapid prototyping
- Sensors, Imagers, MEMS devices
- Measurement, modeling, and simulation of hardware
- CAE, design tools, VLSI design methodology, neural networks
- Packaging and interconnect
- System-level design flow and methodology

SoC

- Network-on-Chip
- Hardware/software co-design and reuse techniques
- Multicore and manycore platforms
- Reconfigurable Architectures
- SoC verification and testing
- Processor and memory design for SoC
- Software runtime environments, emulation and simulation

Papers may be selected for either lecture or poster presentation. Equal quality measures will be applied to posters and lectures. All accepted papers will be published in the conference proceedings and submitted for inclusion in IEEE Xplore.

Papers will be selected by the Steering Committee on the basis of a full-length paper (4-6 A4 pages) based on a peer review made by the Technical Programme Committee. Papers should be submitted no later than 24 August 2018.

Submission of Contributions

The proceedings will be composed from camera ready pdf files supplied by authors. The paper must follow the IEEE standard as described in the "submission of contributions" section at www.norcass.org.

Submitted papers must not exceed six A4 pages, except that there may be a 7th with references only. Papers should be submitted as a pdf file no later than 24 August 2018 (see instructions on www.norcass.org).

Authors will be notified by the end of September 2018. Papers selected for presentation will be presented in conference proceedings which will be made available upon registration. Proceedings and all presentations will be in English.

Location

Tallinn, Estonia

Sponsors:



TAMPERE UNIVERSITY OF TECHNOLOGY

www.norcass.org

CONFERENCE SECRETARIAT:
Technoconsult ApS
Agern Allé 3, DK-2970 Hørsholm,
Tel: +45 2212 5244, Fax: +45 4576 5708
E-mail: info@norcass.org